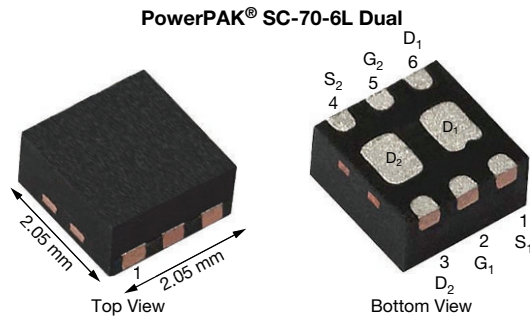


Dual P-Channel 30 V (D-S) MOSFET



Marking code: DO

PRODUCT SUMMARY	
V_{DS} (V)	-30
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10$ V	0.065
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -6$ V	0.080
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5$ V	0.100
Q_g typ. (nC)	4.1
I_D (A) ^a	-4.5
Configuration	Dual

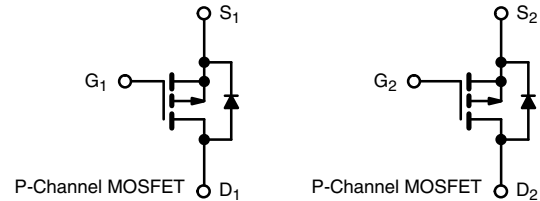
FEATURES

- TrenchFET® Gen III power MOSFET
- Thermally enhanced PowerPAK® SC-70 package
 - Small footprint area
 - Low on-resistance
- 100 % R_g tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
 COMPLIANT
 HALOGEN
FREE

APPLICATIONS

- Smart phones, tablet PCs, mobile computing:
 - Battery switches
 - Load switches
 - Power management
 - DC/DC converters



ORDERING INFORMATION

Package	PowerPAK SC-70
Lead (Pb)-free and halogen-free	SiA931DJ-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	V_{DS}	-30	V
Gate-source voltage	V_{GS}	± 20	
Continuous drain current ($T_J = 150$ °C)	I_D	$T_C = 25$ °C	-4.5 ^a
		$T_C = 70$ °C	-4.5 ^a
		$T_A = 25$ °C	-4.3 ^{b, c}
		$T_A = 70$ °C	-3.4 ^{b, c}
Pulsed drain current ($t = 300$ μ s)	I_{DM}	-28	A
Continuous source-drain diode current	I_S	$T_C = 25$ °C	
		$T_A = 25$ °C	-1.6 ^{b, c}
Maximum power dissipation	P_D	$T_C = 25$ °C	7.8
		$T_C = 70$ °C	5
		$T_A = 25$ °C	1.9 ^{b, c}
		$T_A = 70$ °C	1.2 ^{b, c}
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	°C
Soldering recommendations (peak temperature) ^{d, e}		260	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{b, f}	R_{thJA}	52	65	°C/W
Maximum junction-to-case (drain)	R_{thJC}	12.5	16	

Notes

- Package limited
- Surface mounted on 1" x 1" FR4 board
- $t = 5$ s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 110 °C/W

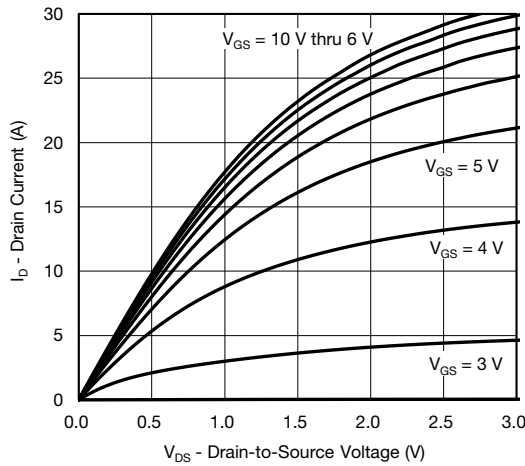
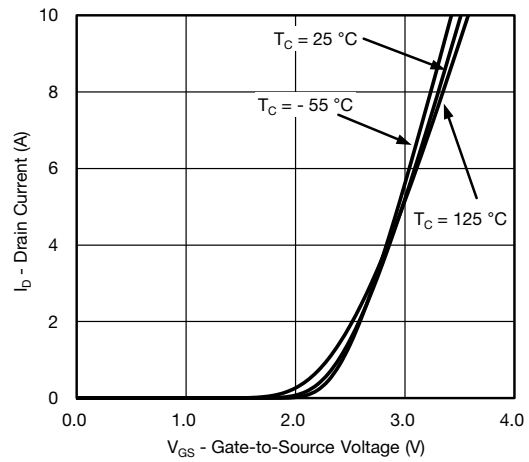
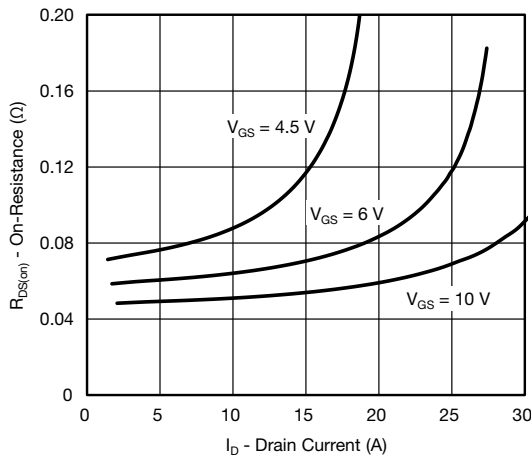
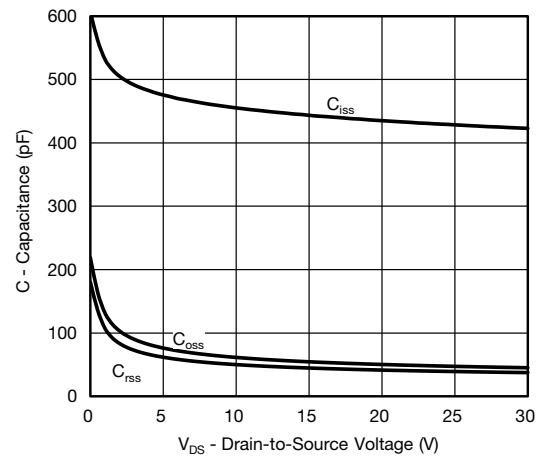
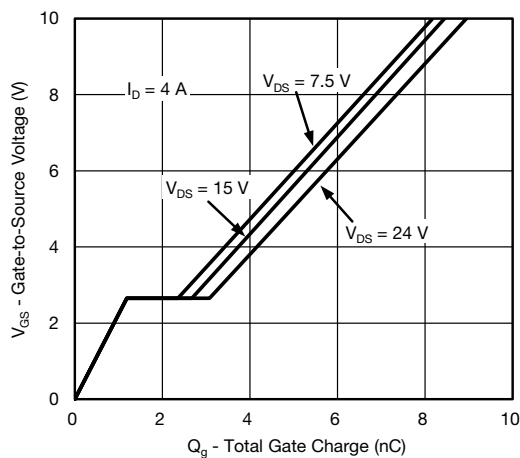
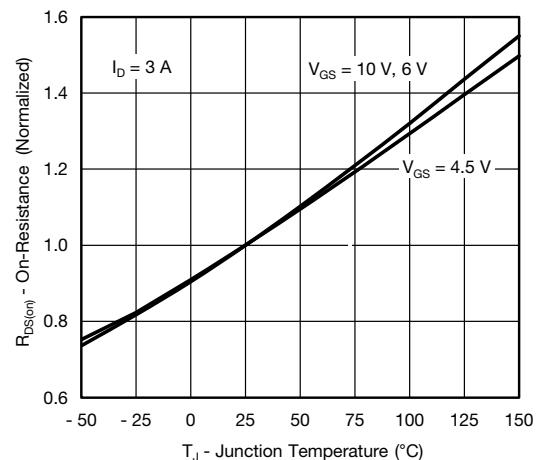


SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-30	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = -250 μA	-	-24	-	mV/°C
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J		-	3.4	-	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-1.2	-	-2.2	V
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V	-	-	-1	μA
		V _{DS} = -30 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	
On-state drain current ^a	I _{D(on)}	V _{DS} ≤ -5 V, V _{GS} = -10 V	-10	-	-	A
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -10 V, I _D = -3 A	-	0.052	0.065	Ω
		V _{GS} = -6 V, I _D = -2 A	-	0.063	0.080	
		V _{GS} = -4.5 V, I _D = -2 A	-	0.077	0.100	
Forward transconductance ^a	g _{fs}	V _{DS} = -15 V, I _D = -3 A	-	8	-	S
Dynamic ^b						
Input capacitance	C _{iSS}	V _{DS} = -15 V, V _{GS} = 0 V, f = 1 MHz	-	445	-	pF
Output capacitance	C _{oss}		-	55	-	
Reverse transfer capacitance	C _{rSS}		-	45	-	
Total gate charge	Q _g	V _{DS} = -15 V, V _{GS} = -10 V, I _D = -4 A	-	8.5	13	nC
		V _{DS} = -15 V, V _{GS} = -4.5 V, I _D = -4 A	-	4.1	6.2	
Gate-source charge	Q _{gs}		-	1.2	-	
Gate-drain charge	Q _{gd}		-	1.5	-	
Gate resistance	R _g	f = 1 MHz	1.1	5.5	11	Ω
Turn-on delay time	t _{d(on)}	V _{DD} = -15 V, R _L = 5 Ω I _D ≅ -3 A, V _{GEN} = -4.5 V, R _g = 1 Ω	-	23	45	ns
Rise time	t _r		-	18	35	
Turn-off delay time	t _{d(off)}		-	17	35	
Fall time	t _f		-	5	10	
Turn-on delay time	t _{d(on)}	V _{DD} = -15 V, R _L = 5 Ω I _D ≅ -3 A, V _{GEN} = -10 V, R _g = 1 Ω	-	8	15	
Rise time	t _r		-	5	10	
Turn-off delay time	t _{d(off)}		-	20	40	
Fall time	t _f		-	5	10	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-4.5	A
Pulse diode forward current	I _{SM}		-	-	-15	
Body diode voltage	V _{SD}	I _S = -3 A, V _{GS} = 0 V	-	-0.9	-1.2	V
Body diode reverse recovery time	t _{rr}	I _F = -3 A, di/dt = 100 A/μs, T _J = 25 °C	-	15	30	ns
Body diode reverse recovery charge	Q _{rr}		-	8	20	nC
Reverse recovery fall time	t _a		-	10	-	ns
Reverse recovery rise time	t _b		-	5	-	

Notes

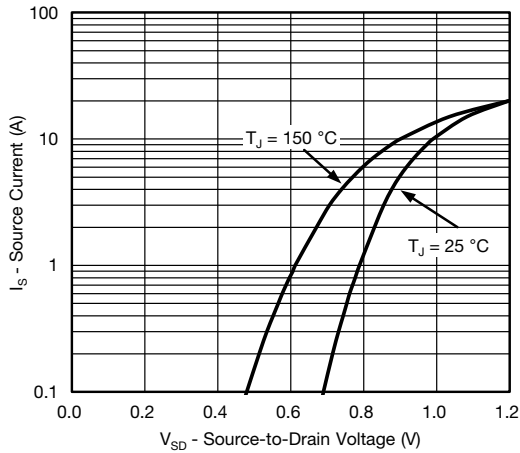
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

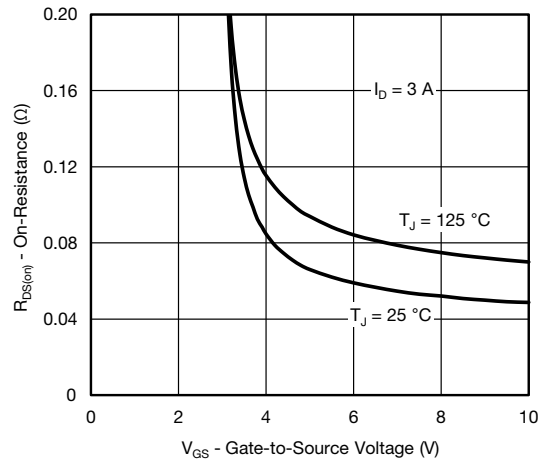
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On-Resistance vs. Drain Current and Gate Voltage

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature



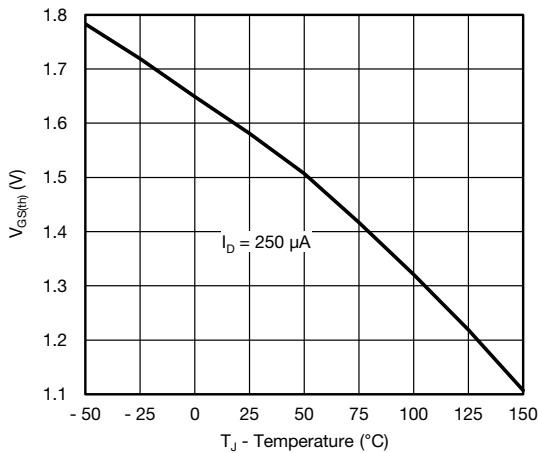
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



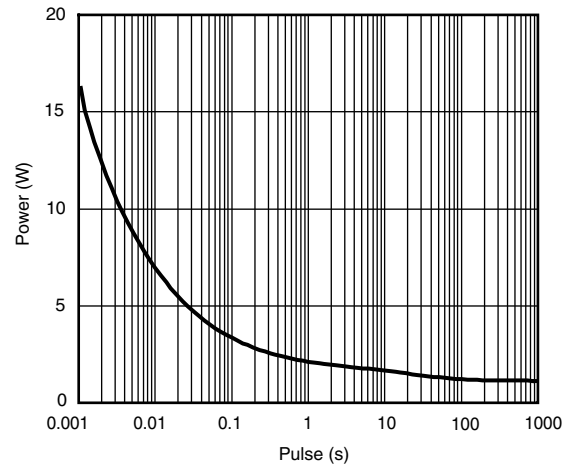
Source-Drain Diode Forward Voltage



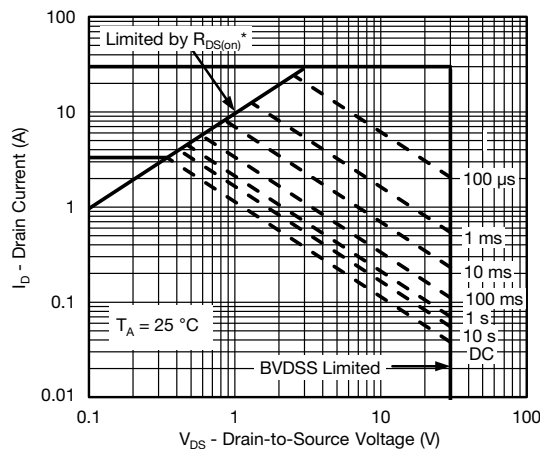
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



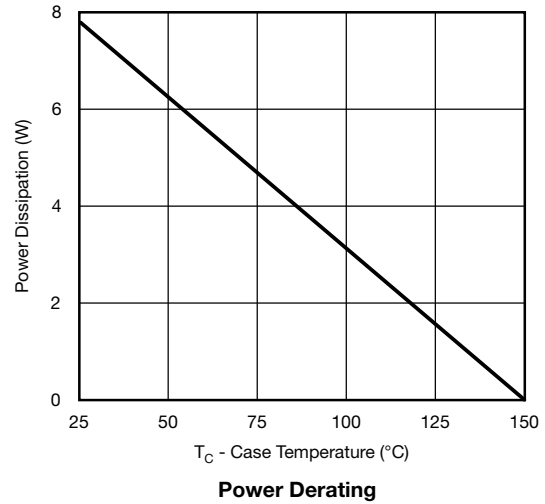
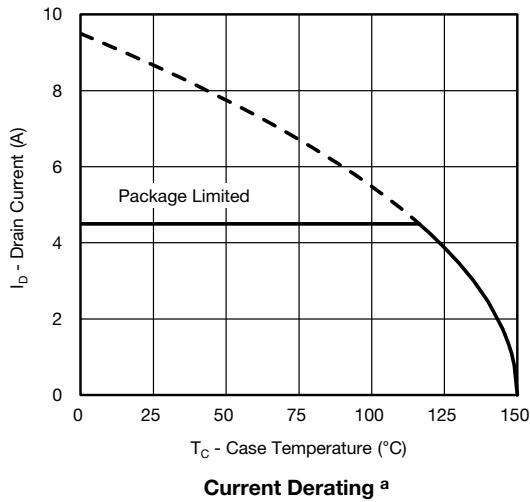
Single Pulse Power, Junction-to-Ambient



Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

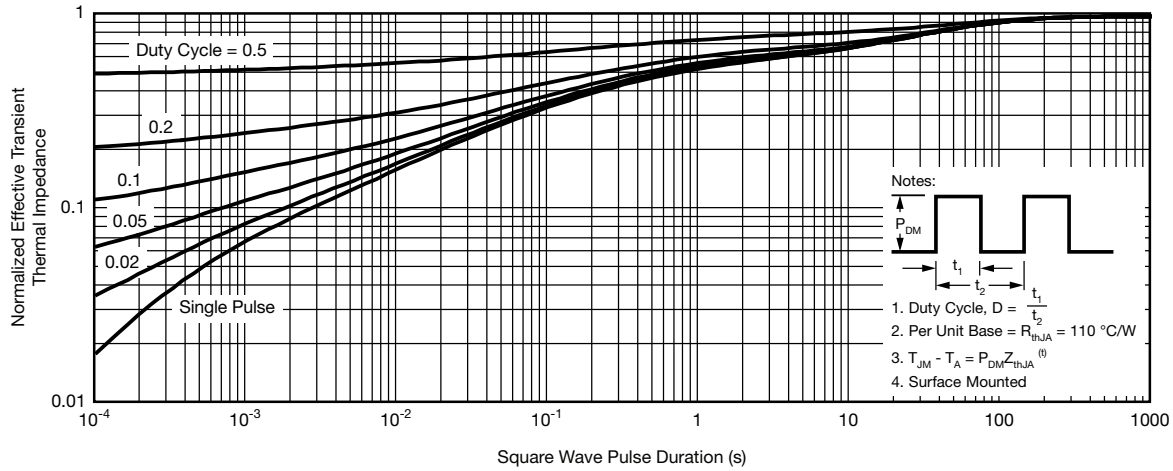


Note

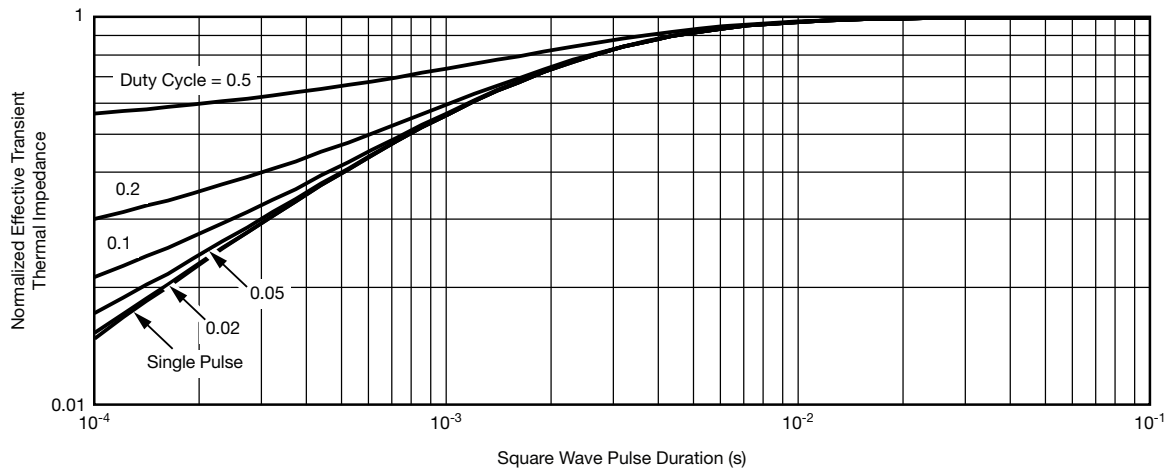
- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62859.



PowerPAK® SC70-6L



BACKSIDE VIEW OF SINGLE



BACKSIDE VIEW OF DUAL



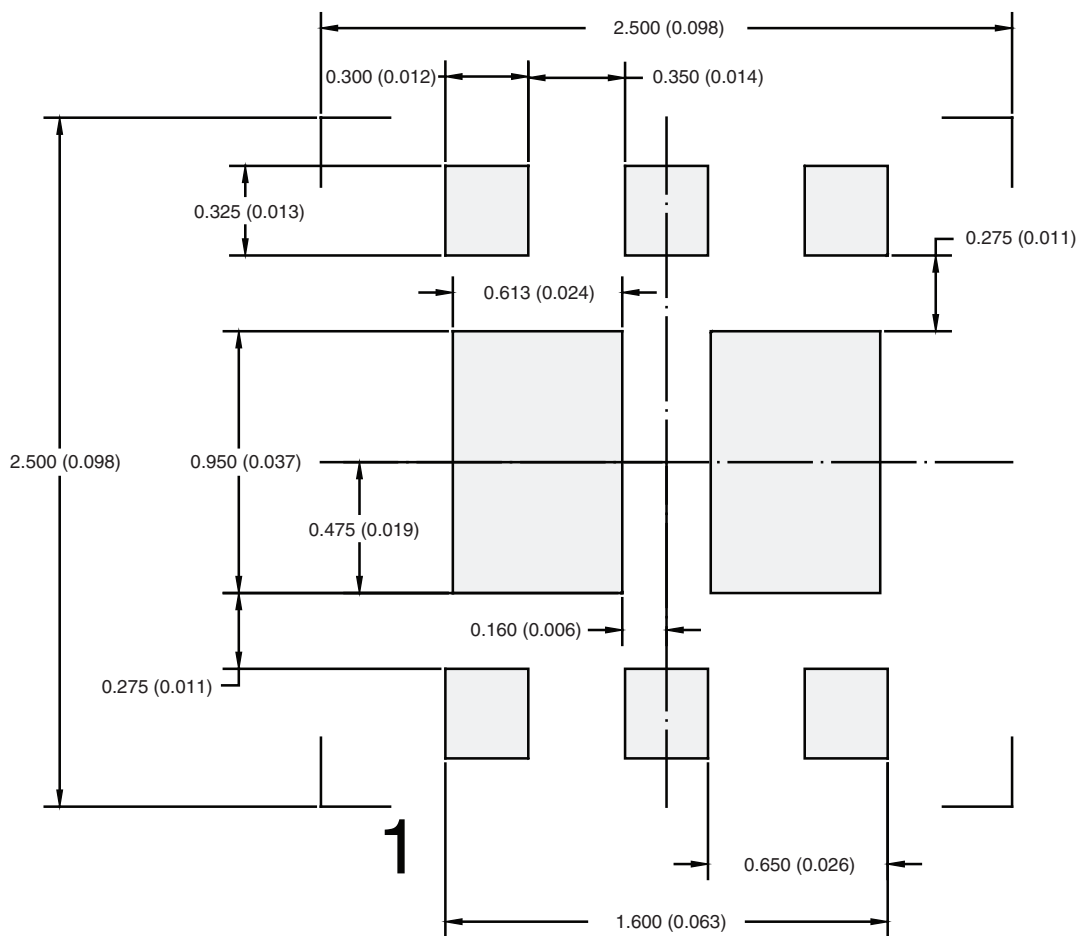
Notes:

1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

DIM	SINGLE PAD						DUAL PAD					
	MILLIMETERS			INCHES			MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
C	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
e	0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC		
K	0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1	0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2	0.240 TYP			0.009 TYP			0.252 TYP			0.010 TYP		
K3	0.225 TYP			0.009 TYP								
K4	0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
T							0.05	0.10	0.15	0.002	0.004	0.006

ECN: C-07431 – Rev. C, 06-Aug-07
 DWG: 5934

RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Dual



Dimensions in mm (inches)

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APPLICATION NOTE



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